PRINTED CIRCUIT BOARDS

INTERCONNECTION CARRIERS

State of the Art: PCB's	Revisio	Datum:	Seite:
PRINTED CIRCUIT BOARDS	01	4.11.2001	1/1

Schematic Key for Multilayer and HDI-Technology Build-Ups

a	b	c	d	e	f	g + h+ i
06	129	FR4	35	L20.35	P06_18_10	S1

columns and equal kind of positions are separated by "_". Equal prefixes in one column are reduced to one.

06_129_FR4_35_L20.35_p06_18_10_s1

Layers	in µ	Material	Build-Up	Assembly
Layer-1	35µ	Copper		B
	100µ	Prepreg	(100 µ PrePreg-Type: 2125)	
	180µ	Prepreg	(180 µ PrePreg-Type: 7628)	
Layer-2	35µ	Copper		A1
	200µ	L-FR4		
Layer-3	35µ	Copper		
	60µ	Prepreg	(60µ PrePreg-Type: 1080)	
	60µ	Prepreg		
Layer-4	35µ	Copper		A2
	200µ	L-FR4		
Layer-5	35µ	Copper		
	180µ	Prepreg		
	100µ	Prepreg		
Layer-99	55µ	Copper		

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